



Designation: **B813—10 B813 – 16**

Standard Specification for Liquid and Paste Fluxes for Soldering of Copper and Copper Alloy Tube ¹

This standard is issued under the fixed designation B813; the number immediately following the designation indicates the year of original adoption or, in the case of revision, the year of last revision. A number in parentheses indicates the year of last reapproval. A superscript epsilon (ϵ) indicates an editorial change since the last revision or reapproval.

This standard has been approved for use by agencies of the U.S. Department of Defense.

INTRODUCTION

This specification covers a series of specific requirements for liquid and paste fluxes. It also incorporates a series of test methods that establish the procedures on how to measure these properties. The format of this specification initially defines the specification requirements followed by the specific test methods in the order in which they are to be performed.

1. Scope—Scope*

1.1 This specification establishes the requirements and test methods for liquid and paste fluxes for joining by soldering of copper and copper alloy tube and fittings in plumbing, heating, air conditioning, mechanical, fire sprinkler, and other similar systems.

NOTE 1—This specification does not apply to fluxes intended for electronic applications.

1.2 Solder fluxes are to be tested in accordance with the requirements of this specification by an independent testing laboratory. Testing, measuring equipment, and inspection facilities shall be of sufficient accuracy and quality to comply with the requirements of this specification.

1.3 *Units*—The values stated in SI units are to be regarded as standard. No other units of measurement are included in this standard.

1.4 The following hazard caveat pertains to Sections 11 – 19. *This standard does not purport to address the safety problems, if any, associated with its use. It is the responsibility of the user of this standard to establish appropriate safety and health practices and determine the applicability of regulatory limitations prior to use.* ¹⁶

2. Referenced Documents

2.1 The following documents of the issue in effect on the date of materials purchase form a part of this specification to the extent referenced herein:

2.2 *ASTM Standards*:²

[B32 Specification for Solder Metal](#)

[B88 Specification for Seamless Copper Water Tube](#)

[B88M Specification for Seamless Copper Water Tube \(Metric\)](#)

[B152/B152M Specification for Copper Sheet, Strip, Plate, and Rolled Bar](#)

[B280 Specification for Seamless Copper Tube for Air Conditioning and Refrigeration Field Service](#)

[B846 Terminology for Copper and Copper Alloys](#)

[D130 Test Method for Corrosiveness to Copper from Petroleum Products by Copper Strip Test](#)

[D1200 Test Method for Viscosity by Ford Viscosity Cup](#)

¹ This specification is under the jurisdiction of Committee B05 on Copper and Copper Alloys and is the direct responsibility of Subcommittee B05.04 on Pipe and Tube. Current edition approved April 1, 2010; May 1, 2016. Published April 2010; May 2016. Originally approved in 1991. Last previous edition approved in 2009 as B813—00; B813 – 10. (2009). DOI: 10.1520/B0813-10; 10.1520/B0813-16.

² For referenced ASTM standards, visit the ASTM website, www.astm.org, or contact ASTM Customer Service at service@astm.org. For *Annual Book of ASTM Standards* volume information, refer to the standard's Document Summary page on the ASTM website.

*A Summary of Changes section appears at the end of this standard

2.3 *Other:*
 1986 Amendments to the Safe Drinking Water Act³

3. General Requirements

3.1 The flux shall be suitable for joining copper tube and fittings by soldering in the size ranges shown in Table 1 of Specifications **B88** and **B88M** and Tables 4 and 5 of Specification **B280**.

3.2 The flux shall remain active over the temperature range of the soldering operation, removing and excluding oxides from the metal surfaces in the joint.

3.3 The flux shall be suitable for use with all solders listed in Table 5 of Specification **B32** as well as the more recently developed solder alloys suitable for the applications in the scope of this specification.

3.4 The flux shall allow the solder to adequately wet and spread on the surfaces being soldered.

3.5 The flux residue shall be water flushable after soldering as specified in accordance with Sections **7** and **9**.

3.6 The flux residue shall not be corrosive or toxic after soldering potable water systems.

3.7 The flux shall not release toxic fumes during the soldering operation or corrosive or toxic substances into the water inside or outside the completed system.

3.8 The flux shall adhere to the copper and copper alloys under anticipated temperature, joint geometry, joint position, job site, and weather conditions.

3.9 The flux shall not contain more than 0.2 % lead in accordance with the 1986 Amendments to the Safe Drinking Water Act.

3.10 In the case of Tinning flux, if the unalloyed flux meets the requirements of this specification, then the Tinning flux shall be deemed to meet the requirements of this specification.

4. Terminology

4.1 For terms related to copper and copper alloys, refer to Terminology **B846** for terms specific to this standard.

4.2 *Definitions:*

4.2.1 *flux, n*—a chemically active substance that is used to remove and exclude oxides from the joint area during heating and that ensures that the melted solder will wet the surfaces to be joined.

4.2.2 *tinning flux, n*—a flux as described in 4.2.1, containing tin alloy powder at a maximum level of 10 % by weight of flux.

5. Spreading Factor

5.1 Spreading of the solder is determined by measuring the height (h) of a solder bead on a standard test sheet following the specified heating cycle. Spread factor (SF) is calculated as follows:

$$SF = 100(1.0 - h) \quad (1)$$

where:

h = the maximum height of the solder bead, mm.

5.2 A flux is considered to have acceptably influenced the spreading of solder on the copper surfaces when the average spreading factor is at least 50 (see Section **13**).

5.3 The spreading test shall show a balanced action by forming a regular and even solder layer.

6. Aggressiveness Requirements

6.1 From a standard test sheet on which a specimen has been prepared with solder (see Section **15**), the resistivity of the aqueous solution shall be more than 100 000 Ω cm.

6.2 From a standard test sheet on which a specimen has been prepared without solder (see Section **16**), the resistivity of the aqueous solution shall be more than 85 000 Ω cm.

7. Corrosiveness Requirements

7.1 There shall be a clear indication that in the areas of flux reaction, the sheets shall show a corrosion and residue-free surface comparable with the unwetted areas as determined by visual inspection in accordance with Section **17**.

7.2 Corrosiveness shall be reported in accordance with one of the classifications listed as follows (see Test Method **D130**):

³ Available from U.S. Government Printing Office Superintendent of Documents, 732 N. Capitol St., NW, Mail Stop: SDE, Washington, DC 20401, [http://www.access.gpo.gov](http://www.access.gpo.gov/Publishing Office, 732 North Capitol Street, NW, Washington, DC 20401-0001, www.gpo.gov).

Classification	Description
4	Slight tarnish
1	Slight tarnish
2	Moderate tarnish
2	Moderate tarnish
3	Dark tarnish
3	Dark tarnish

8. Viscosity Requirements

8.1 The viscosity of liquid fluxes shall be less than 180 s as determined using a No. 2 Ford flow cup in accordance with Section 18.

9. Residue Flushing Requirements

9.1 Flushing of the residue shall be determined by weight loss.

9.2 The loss of weight of each sheet shall be determined by comparing the average weight before and after the test procedure. The weight loss of the flux residue shall be more than 99 % in accordance with Section 19.

$$\% \text{ Weight Loss } (d) = 100 - \frac{(c - a)}{(b - a)} \times 100 \quad (2)$$

where:

- a* = weight of degreased, flushing-test sheet, g;
- b* = weight of degreased, flushing-test sheet plus the weight of applied flux, g; and
- c* = weight of dried, flushing-test sheet after flushing, g.

10. Sampling

10.1 Samples of flux taken for the purpose of the tests listed in this specification shall be selected from the stock of the manufacturer and shall be representative of the material being evaluated.

11. Specimen Preparation

11.1 *Standard Quantity of Solder Metal*—A standard quantity of solder metal shall be a sample of 60:40 tin-lead (Alloy Grade Sn60), measuring 6.0 mm in diameter by 0.86 mm in thickness, weighing approximately 0.21 g, that has been degreased with trichloroethylene.

11.2 *Standard Quantity of Flux*—A standard quantity of flux shall be 0.003 mL as measured by a precision pipet or other volumetric measuring devices with equivalent precision.

11.2.1 *Standard Quantity of Tinning Flux*—A standard quantity of Tinning flux shall be the same as described in 11.2, with a maximum of 10 % tinning powder added to it.

11.3 *Standard Test Sheet*—A standard test sheet shall be a piece of copper 35 by 35 by 1 mm thick of Copper UNS No. C12200 (deoxidized high residual phosphorus) produced in accordance with Specification B152/B152M.

11.3.1 Preparation:

11.3.1.1 The sheet is abraded three times with a waterproof sand or emery paper (Grit No. 360), each time perpendicular to the previous direction. One corner of each test sheet shall be bent upwards to permit handling. It is degreased with calcium carbonate mixed with water to a paste consistency with which the test sheet is rubbed using a wad of cotton. The residue is flushed off by a strong jet of tap water. The test sheet is considered to be degreased when it is completely moistened by water when flushed.

11.3.1.2 In any of the following steps in which the test sheets must be handled, use forceps or laboratory tongs. The sheet is then etched for 15 s in an etching solution formulated as follows:

(a) *Etching Solution*—(1-L etching solution contains 200-g chromic acid anhydride (CrO₃) and 125-mL sulfuric acid (specific gravity 1.84) reagent grade, balance distilled water, diluted to 1 L.)

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(b) Finally, the sheet is rinsed thoroughly with distilled water (60 to 70°C), immersed in ethanol (ACS Grade), and allowed to dry.

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11.4 *Resistivity Test Specimen*—The resistivity test specimen is the condition of the standard test sheet on which have been deposited standard quantities of flux and solder metal before they are placed in the oven. In the case of Tinning flux, specimen should be prepared without tinning powder added to the base flux.

11.4.1 Preparation:

11.4.1.1 Remove test sheet from the liquid ethanol, allow to dry, and apply a standard quantity of flux. With a standard quantity of solder metal, spread the flux to an area of about ~~15 mm~~ 15 mm in diameter.

11.4.1.2 Place the test sheet with flux and solder metal in the oven where it remains for 3 min at a temperature of 275°C from the time the solder melts. Remove the specimen and allow to cool to room temperature.

11.5 *Flushing-Test Sheet*—The flushing-test sheet is a piece of copper 100 by 100 by 1.0 mm thick of Copper UNS No. C12200 (deoxidized high residual phosphorus) produced in accordance with ~~Specifications~~ Specification **B152/B152M**.

11.5.1 *Preparation:*

11.5.1.1 The copper sheets shall have raised edges of 3 or ~~4 mm~~ 4 mm to avoid loss of flux. The sheets shall be degreased with trichloroethylene, flushed with water, and dried at a temperature of 50°C. Every sheet shall be weighed to 10-mg accuracy using a standard laboratory balance.

12. Test Methods

12.1 The properties enumerated in this specification shall be determined in accordance with the test methods given in Sections **13 – 19**.

13. Spreading Test

13.1 *Scope*—The influence of the flux on the spreading of the fluid solder is indicated by the spreading factor obtained by the conditions detailed in Section **17**.

13.2 *Apparatus:*

13.2.1 *Oven*—The performance characteristics of the oven shall be such that the temperature has an accuracy of $\pm 2.5^\circ\text{C}$. The oven shall be equipped with a sight glass for visible control of the melting of the solder. It shall be possible to measure the oven temperature in close proximity to the test sheet. The test sheet shall be capable of being placed in the oven and removed from it exactly horizontally. To reduce cooling when the preheated test sheet is removed from the oven, it is placed on a plate in an exact horizontal position so as to be pushed in and out. The oven must be easy to heat to the preset temperature.

13.2.2 *Gilson Precision Pipet*, 3 to 25 μL .

13.3 *Spreading Factor Procedure:*

13.3.1 The spreading factor test specimen is the condition of the standard test sheet with a standard quantity of flux having been heated to 275°C for 30 s in the oven. Immediately afterwards, a standard quantity of solder metal is placed over the liquid flux and the test specimen is replaced in the oven. In the case of Tinning flux, specimen should be prepared without tinning powder added to the base flux.

13.3.2 The period for which the test sheet shall be outside the oven for application of the solder metal shall not exceed ~~10 s~~ 10 s.

13.3.3 Remove test sheet from the ethanol, allow to dry, and apply a standard quantity of flux. Spread the flux with a standard quantity of solder metal to an area of about 15 mm in diameter and then remove the solder metal.

13.3.4 Heat the test sheet with flux for 30 s in an oven at 275°C. Afterwards, replace the standard quantity of solder metal that was used to spread the flux on the test sheet and heat the assembly for 3 min at a temperature of 275°C in the oven.

13.3.5 After the test specimen has cooled to room temperature and been cleaned, measure the solder height by means of a flat micrometer three times, average the values, and calculate the spreading factor as in **5.1**.

13.4 *Calculation*—After five tests, the highest and lowest figures are excluded. Calculate the average of the remaining three.

14. Aggressiveness Test

14.1 *Scope*—The aggressiveness of the flux is determined by means of a resistivity test by measuring the resistivity in $\Omega\text{-cm}$ of an aqueous solution of the flux residue. In the case of Tinning flux, specimen should be prepared without tinning powder added to the base flux. The conductivity cell to be used shall be kept immersed in distilled water at ambient temperature for a minimum of 24 h before use.

14.2 *Apparatus:*

14.2.1 *Ohmmeter (Must Be Suitable for Use with Liquids)*—Cell constant shall be specified.

14.2.2 *Beakers—100 mL*—for this test shall be acid/alkali resistant, cleaned, and degreased. Finally, they shall be rinsed thoroughly with distilled water.

14.2.3 *Thermometers*—The temperatures shall be measured with cleaned thermometers having a scale that will accurately register the temperatures. The thermometer shall be immersed in a clean graduate measuring cylinder, filled with distilled water for a minimum of 24 h before use.

14.3 *Calculation*—After five tests, the highest and lowest figures are excluded and the average of the other three is used.

15. Resistivity Test—Soldered (see **6.1**)

15.1 *Procedure:*

15.1.1 Clean seven watch glasses and seven graduated beakers thoroughly by washing in hot water detergent solution, rinsing several times with tap water followed by rinsing three times with distilled water. Then add approximately 50 mL of distilled water